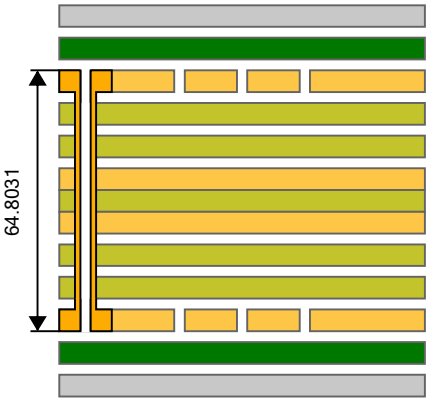


Layer	Stack up	Description	Impedance ID	Base Thickness	Finish Thickness	Mask Thickness	Type	ϵ_r	
1		Screened Ident					Ident		
		Liquid PhotoImageable Mask				0.984	SolderMask	4.000	
		Copper Foil	1, 2	1.378	1.378		Copper		
		FR4		3.307	3.307			4.300	
2		FR4		2.717	2.717			4.300	
3		FR4		1.378	1.378			4.300	
4		FR4		47.244	47.244			4.300	
		FR4		1.378	1.378			4.300	
		FR4		2.717	2.717			4.300	
		FR4		3.307	3.307			4.300	
4		Copper Foil	3	1.378	1.378		Copper		
		Liquid PhotoImageable Mask				0.984	SolderMask	4.000	
		Screened Ident					Ident		

Copper Thickness = 5.512 | Dielectric Thickness = 59.291 | Overall Processed Thickness = 64.803

Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width	Trace Separation	Ground Strip Separation	Target Impedance	Calculated Impedance	Tol (+/- %)
1	Coated Microstrip 1B	1	2	0	9.700	0.000	0.000	50.000	49.940	10.000
2	Coated Coplanar Strips With Lower Ground 1B	1	2	0	8.800	0.000	9.000	50.000	50.360	10.000
3	Coated Microstrip 1B	4	3	0	9.700	0.000	0.000	50.000	49.940	10.000

Notes

StackName: 2-Layer	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 2/2	
Date: 11-02-2023	Associated Documents:						
Author:							
Department:							
Site:							